

Title (en)

METHOD, DEVICE AND INSTALLATION FOR PRODUCING PRINTED CIRCUIT BOARDS

Title (de)

VERFAHREN, VORRICHTUNG UND ANLAGE ZUR LEITERPLATTENHERSTELLUNG

Title (fr)

PROCÉDÉ, DISPOSITIF ET INSTALLATION DE FABRICATION DE CARTES DE CIRCUITS IMPRIMÉS

Publication

EP 3659408 A1 20200603 (DE)

Application

EP 18740745 A 20180629

Priority

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- EP 2018067715 W 20180629

Abstract (en)

[origin: WO2019020318A1] In a method for producing printed circuit boards, a substrate (112), which has a carrier layer made of an electrically insulating material and an electrically conductive layer applied thereto, is processed in a plurality of steps. To carry out a development step and/or an etching step, the substrate (112) is rotated. A developer solution and/or an etching liquid is applied to the rotating substrate (112) by means of at least one nozzle (113). In addition to the method, a device suitable for carrying out the method and an installation comprising the device are described.

IPC 8 full level

H05K 3/06 (2006.01)

CPC (source: EP KR US)

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